Multi Purpose Axial Leaded Glass Schottky Diodes

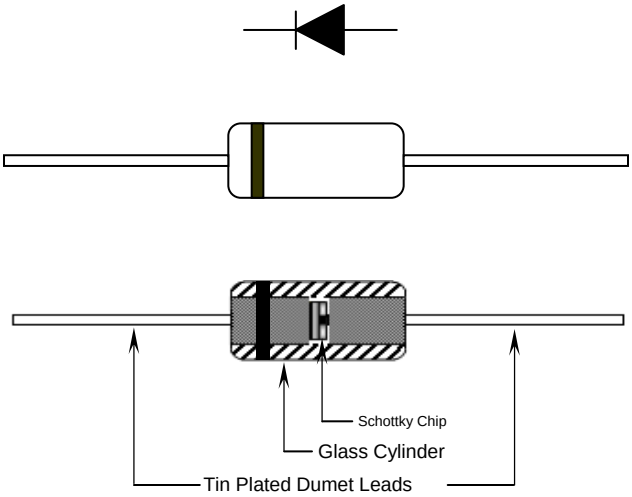
V2

Features

- Glass Hermetically Sealed Packages
- Picosecond Switching
- Low Leakage Current
- Offered in Tape and Reel Packaging
- RoHS Compliant

Glass Package Style

ODS 54



Description and Applications

These Schottky diodes are designed to have pico-second switching speed and are housed in a hermetic axial lead glass package. These devices are designed for use in a variety of applications including mixing, detecting, and switching at both low and high power levels. They can also be used in commercial switching and control functions particularly in narrow band receivers. They can also be used in low frequency applications such as shaping, sampling, and as gates.

Absolute Maximum Ratings

T_{AMB} = +25°C (Unless Otherwise Noted) [1]

Parameter	Absolute Maximum
D.C. Reverse Voltage	(See Table)
Operating Temperature	-65°C to +200°C
Storage Temperature	-65°C to +200°C
Installation Temperature	+230°C for 5 Seconds
Power Dissipation Listed Below Will De-Rate Linearly to 0mW at 135°C	
Case Style 54	250mW

Notes

1. Operation of this device above any one of these parameters may cause permanent damage.

Ordering Information

Part Number	Package	Standard Quantity
MA4E2811	ESD Bags	Bulk
MADS-002811-00540T	Tape and Reel	1500
MA4E2812-54	ESD Bags	Bulk

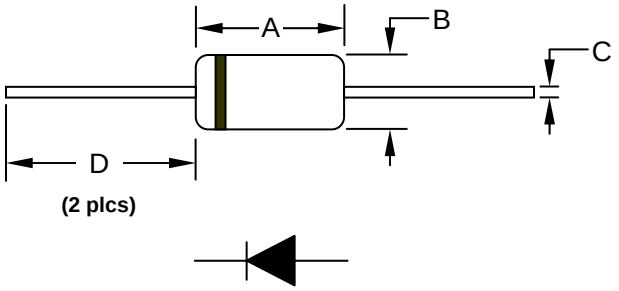
• **North America** Tel: 800.366.2266 • **Europe** Tel: +353.21.244.6400
• **India** Tel: +91.80.43537383 • **China** Tel: +86.21.2407.1588
Visit www.macomtech.com for additional data sheets and product information.

Multi Purpose Axial Leaded Glass Schottky Diodes V2

Diode Specifications *

Part Number	Package Style	Voltage Breakdown @ 10uA Vb (min.)	Forward Voltage @ 1mA Vf (max.)	Forward Voltage @ 20mA Vf (max.)	Forward Voltage @ 35mA Vf (max.)	Reverse Leakage Current @ 8 V Ir (max.)	Reverse Leakage Current @ 15 V Ir (max.)	Capacitance @ 0V, F=1MHz Ct (max.)
MADS-002811-00540T MA4E2811	54	15 V	410 mV	1.0 V	-	100 nA	-	1.2 pF
MA4E2812-54	54	20 V	550 mV	-	1.0 V	-	150nA	1.2 pF

Package Outline Dimensions



Package Style	Dimension A		Dimension B		Dimension C		Dimension D (Min.)	
	Mils	mm	Mils	mm	Mils	mm	Mils	mm
54	155 ± 10	3.94 ± .25	71 ± 3	1.8 ± .08	15 ± 1	.38 ± .03	1000	25.4

Assembly Recommendations

- Leads on axial leaded devices must be formed while being held firm. Bending the leads too close to the body of the part may cause internal damage to the device. Bends <0.060" from body are not recommended. Appropriate fixturing should be used.
- Devices may be soldered using standard 60/40, Sn/Pb or RoHS compliant solders. Axial leads are tin plated, 50μM, thick to ensure an optimum connection.

*** Specifications subject to change without notice.**

• **North America** Tel: 800.366.2266 • **Europe** Tel: +353.21.244.6400
• **India** Tel: +91.80.43537383 • **China** Tel: +86.21.2407.1588
Visit www.macomtech.com for additional data sheets and product information.